

ABSTRACT

A die comprising; a substrate; two or more various shaped bump structures having a solder line formed over the substrate; and an epoxy layer formed over the substrate. The epoxy layer having a top surface wherein: (a) the solder lines are below the top surface of the epoxy layer'; (b) the solder lines are above the top surface of the epoxy layer; or (c) some of the solder lines are below the top surface of the epoxy layer and some of the solder lines are above the top surface of the epoxy layer.